

January 2008

74AC273, 74ACT273 Octal D-Type Flip-Flop

Features

- Ideal buffer for microprocessor or memory
- Eight edge-triggered D-type flip-flops
- Buffered common clock
- Buffered, asynchronous master reset
- See 377 for clock enable version
- See 373 for transparent latch version
- See 374 for 3-STATE version
- Outputs source/sink 24mA
- 74ACT273 has TTL-compatible inputs

General Description

The AC273 and ACT273 have eight edge-triggered D-type flip-flops with individual D-type inputs and Q outputs. The common buffered Clock (CP) and Master Reset $(\overline{\text{MR}})$ input load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D-type input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the $\overline{\text{MR}}$ input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Ordering Information

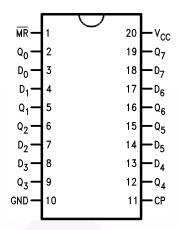
Order Number	Package Number	Package Description
74AC273SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74AC273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC273MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC273PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT273SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACT273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT273MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

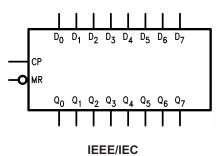
Connection Diagram



Pin Description

Pin Names	Description
D ₀ –D ₇	Data Inputs
MR	Master Reset
СР	Clock Pulse Input
Q ₀ –Q ₇	Data Outputs

Logic Symbols



Mode Select-Function Table

	ı	nputs	Outputs	
Operating Mode	MR	СР	D _n	Q _n
Reset (Clear)	L	Х	Х	L
Load '1'	Н	~	Н	Н
Load '0'	Н	~	L	L

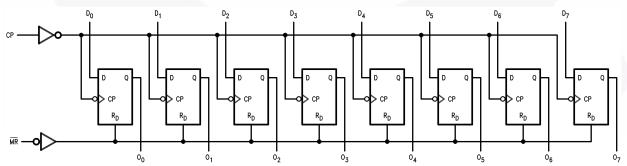
H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

∠ = LOW-to-HIGH Transition

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current	
	$V_{I} = -0.5V$	–20mA
	$V_{I} = V_{CC} + 0.5$	+20mA
V _I	DC Input Voltage	-0.5V to V _{CC} + 0.5V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
Vo	DC Output Voltage	-0.5V to V _{CC} + 0.5V
Io	DC Output Source or Sink Current	±50mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
TJ	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	
	AC	2.0V to 6.0V
	ACT	4.5V to 5.5V
VI	Input Voltage	0V to V _{CC}
Vo	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	-40°C to +85°C
ΔV / Δt	Minimum Input Edge Rate, AC Devices:	125mV/ns
	V_{IN} from 30% to 70% of V_{CC} , V_{CC} @ 3.3V, 4.5V, 5.5V	
ΔV / Δt	Minimum Input Edge Rate, ACT Devices:	125mV/ns
	V _{IN} from 0.8V to 2.0V, V _{CC} @ 4.5V, 5.5V	

DC Electrical Characteristics for AC

				T _A = -	+25°C	T _A = -40°C to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	3.0	$V_{OUT} = 0.1V$ or	1.5	2.1	2.1	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V _{IL}	Maximum LOW Level	3.0	$V_{OUT} = 0.1V$ or	1.5	0.9	0.9	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V _{OH}	Minimum HIGH Level	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V _{OL}	Maximum LOW Level	3.0	$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I _{IN} ⁽²⁾	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽³⁾	5.5	V _{OHD} = 3.85V Min.			– 75	mA
I _{CC} ⁽²⁾	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC} .
- 3. Maximum test duration 2.0ms, one output loaded at a time.

DC Electrical Characteristics for ACT

				T _A = -	+25°C	$T_A = -40$ °C to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V _{CC} – 0.1V	1.5	2.0	2.0	
V _{IL}	Maximum LOW	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Level Input Voltage	5.5	V _{CC} – 0.1V	1.5	0.8	0.8	
V _{OH}	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V _{OL}	Maximum LOW	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Level Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I _{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{CCT}	Maximum I _{CC} /Input	5.5	$V_{I} = V_{CC} - 2.1V$	0.6		1.5	mA
I _{OLD}	Minimum Dynamic	5.5	$V_{OLD} = 1.65V Max.$			75	mA
I _{OHD}	Output Current ⁽⁵⁾	5.5	V _{OHD} = 3.85V Min.			- 75	mA
I _{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

AC Electrical Characteristics for AC

			T _A = +25°C, C _L = 50pF		$T_A = -40$ °C to +85°C, $C_L = 50$ pF			
Symbol	Parameter	V _{CC} (V) ⁽⁶⁾	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock Frequency	3.3	90	125		75		MHz
		5.0	140	175		125		
t _{PLH}	Propagation Delay,	3.3	4.0	7.0	12.5	3.0	14.0	ns
	Clock to Output	5.0	3.0	5.5	9.0	2.5	10.0	
t _{PHL}	Propagation Delay,	3.3	4.0	7.0	13.0	3.5	14.5	ns
	Clock to Output	5.0	3.0	5.0	10.0	2.5	11.0	
t _{PHL}	Propagation Delay,	3.3	4.0	7.0	13.0	3.5	14.0	ns
	MR to Output	5.0	3.0	5.0	10.0	2.5	10.5	

Note:

6. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V.

AC Operating Requirements for AC

			T _A = +25°C, C _L = 50pF		$T_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C},$ $C_{L} = 50\text{pF}$	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Тур.	Gu	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW,	3.3	3.5	5.5	6.0	ns
	Data to CP	5.0	2.5	4.0	4.5	
t _H	Hold Time, HIGH or LOW,	3.3	-2.0	0	0	ns
	Data to CP	5.0	-1.0	1.0	1.0	
t _W	Clock Pulse Width, HIGH or LOW	3.3	3.5	5.5	6.0	ns
		5.0	2.5	4.0	4.5	
t _W	MR Pulse Width, HIGH or LOW	3.3	2.0	5.5	6.0	ns
		5.0	1.5	4.0	4.5	
t _{rec}	Recovery Time, MR to CP	3.3	1.5	3.5	4.5	ns
		5.0	1.0	2.0	3.0	

Note

7. Voltage range 3.3 is $3.3V \pm 0.3V$. Voltage range 5.0 is $5.0V \pm 0.5V$.

AC Electrical Characteristics for ACT

			T _A = +25°C, C _L = 50pF		$T_A = -40$ °C to +85°C, $C_L = 50$ pF			
Symbol	Parameter	V _{CC} (V) ⁽⁸⁾	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock Frequency	2.0	125	189		110		MHz
t _{PLH} , t _{PHL}	Propagation Delay, CP to Q _n	5.0	1.5	6.5	8.5	1.5	9.0	ns
t _{PHL}	Propagation Delay, MR to Q _n	5.0	1.5	7.0	9.0	1.5	8.5	ns

Note:

8. Voltage range 5.0 is $5.0V \pm 0.5V$.

AC Operating Requirements for ACT

			T _A = +25°C, C _L = 50pF		5°C, $T_A = -40$ °C to +85°C, $C_L = 50$ pF	
Symbol	Parameter	V _{CC} (V) ⁽⁹⁾	Тур.	Gua	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW, D _n to CP	5.0	1.0	3.5	3.5	ns
t _H	Hold Time, HIGH or LOW, D _n to CP	5.0	-0.5	1.5	1.5	ns
t _W	Clock Pulse Width, HIGH or LOW	5.0	2.0	4.0	4.0	ns
t _W	MR Pulse Width, HIGH or LOW	5.0	1.5	4.0	4.0	ns
t _W	Recovery Time, MR to CP	5.0	0.5	3.0	3.0	ns

Note:

9. Voltage range 5.0 is $5.0V \pm 0.5V$.

Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C _{IN}	Input Capacitance	V _{CC} = OPEN	4.5	pF
C _{PD}	Power Dissipation Capacitance for AC	V _{CC} = 5.0V	50.0	pF
	Power Dissipation Capacitance for ACT		40.0	

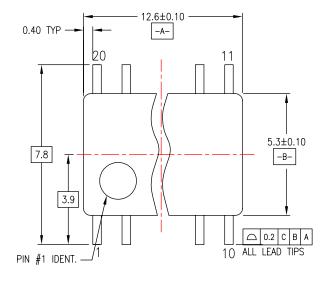
Physical Dimensions 13.00 12.60 11.43 9.50 10.65 7.60 10.00 7.40 0.51 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 С 0.20 △ 0.10 C 0.30 0.10 0.75 0.25 × 45° NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 1.27 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L -(1.40) F) DRAWING FILENAME: MKT-M20BREV3 DETAIL A

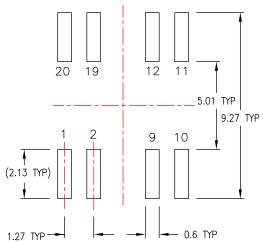
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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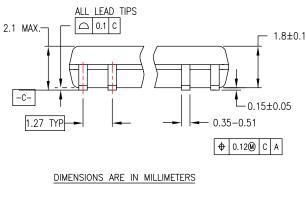
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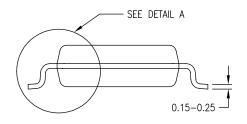
Physical Dimensions (Continued)





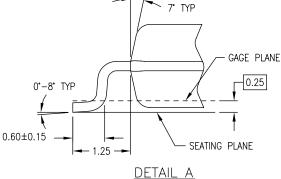
LAND PATTERN RECOMMENDATION





NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M20DREVC

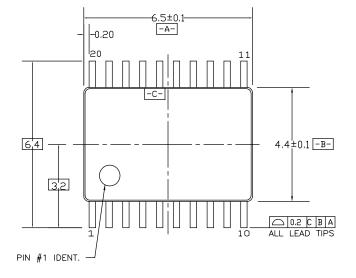
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

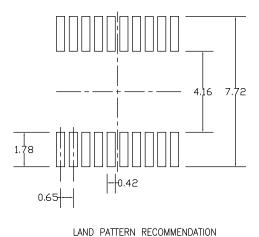
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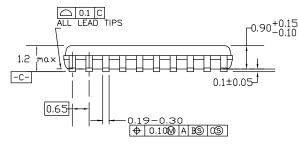
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Physical Dimensions (Continued)







DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE $7/93.\,$
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

0 - 8°7 GAGE PLANE 0 - 8°7 SEATING PLANE R0.09min DETAIL A

SEE DETAIL A

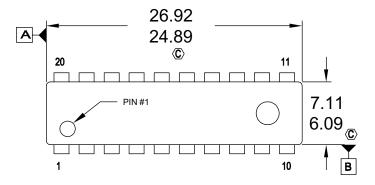
MTC20REVD1

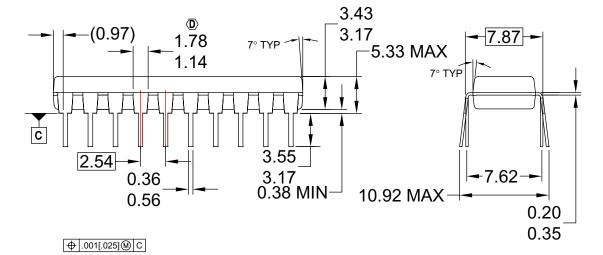
Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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Physical Dimensions (Continued)





NOTES:
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VARIATIONS AD.

B. ALL DIMENSIONS ARE IN MILLIMETERS

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MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED

0.25MM.

(D. DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED

E. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994. F. DRAWING FILE NAME: N20AREV8

Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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